Elbara O Ziade

List of Publications by Year in descending order

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FIRADA O ZIADE

#	Article	IF	CITATIONS
1	Uncertainty analysis of thermoreflectance measurements. Review of Scientific Instruments, 2016, 87, 014901.	1.3	90
2	Thermal conductance imaging of graphene contacts. Journal of Applied Physics, 2014, 116, .	2.5	69
3	Thickness dependent thermal conductivity of gallium nitride. Applied Physics Letters, 2017, 110, .	3.3	67
4	Modeling optical absorption for thermoreflectance measurements. Journal of Applied Physics, 2016, 119, .	2.5	23
5	Integrating sustainable biofuel and silver nanomaterial production for in situ upgrading of cellulosic biomass pyrolysis. Energy Conversion and Management, 2017, 142, 143-152.	9.2	22
6	Wide bandwidth frequency-domain thermoreflectance: Volumetric heat capacity, anisotropic thermal conductivity, and thickness measurements. Review of Scientific Instruments, 2020, 91, 124901.	1.3	10
7	Thermal conductance of nanoscale Langmuir-Blodgett films. Applied Physics Letters, 2015, 107, 221603.	3.3	7
8	Simultaneous thickness and thermal conductivity measurements of thinned silicon from 100 nm to 17 <i>μ</i> m. Applied Physics Letters, 2021, 118, .	3.3	5
9	Thermal conductivity of (Ge2Sb2Te5)1â~'xCx phase change films. Journal of Applied Physics, 2020, 128, 155106.	2.5	4
10	Non ontact Mass Density and Thermal Conductivity Measurements of Organic Thin Films Using Frequency–Domain Thermoreflectance. Advanced Materials Interfaces, 2022, 9, .	3.7	4
11	Sensing depths in frequency domain thermoreflectance. Journal of Applied Physics, 2022, 131, .	2.5	2
12	Development of conductive fusion technology : Advanced die attach materials for high power applications. , 2017, , .		1
13	Imaging Thermal Transport in Graphene. Journal of Heat Transfer, 2015, 137, .	2.1	0
14	Mapping Thickness Dependent Thermal Conductivity of GaN. Journal of Heat Transfer, 2016, 138, .	2.1	0
15	Development of Conductive Fusion Technology Advanced Die Attach Materials for High Power Applications. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2017, 2017, 000094-000098.	0.2	0